

EMERGENCY PHONE 1-800-255-3924
TECHNICAL DATA SHEETS
MP 5405NS

Description:

MP5405NS is a two part unfilled epoxy adhesive designed for high speed bonding of metals, ceramics, and most plastics. It cures to a tough semi-rigid material, and is a thixotropic paste consistency to prevent running and sagging. It gives good resistance to water, salt spray, inorganic acids and bases, and most organic solvents. It was especially formulated to a 1:1 mix ratio for use in either MMD equipment or side-by-side dual cartridges for easy dispensing.

A handling cure is normally achieved at room temperature within 20 - 30 minutes with full cure in 24 hours. An elevated temperature cure schedule can be used to reach final properties quickly.

Handling and Storage:

- 1) Bring both components to room temperature prior to mixing. Mix 1 parts A to 1 part B thoroughly.
- 2) Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
- 3) Clean up uncured resin with suitable organic solvent such as MEK, acetone or a chlorinated solvent.

Mix Ratio:

1A:1B by weight or 1A:1B by volume.

Shelf Life:

12 Months

Handling Characteristics:

All properties given are at 25C unless otherwise noted.

Color	Translucent/White
Viscosity Part A	1,500,000 cps
Part B	1,500,000 cps
Mixed	Non-sag Paste
Specific Gravity Part A	1.17
Part B	1.15
Mixed	1.16
Pot Life	3 - 5 minutes
Mass	20 grams
Tensile Strength Lap Shear (Al to Al)	2800 psi
Tensile Elongation	3 - 5% *
Tensile Strength Temperature Range	7000 psi * -40 to 130C
Hardness Method	80 Shore -D
Linear Coefficient of Thermal Expansion	(x 10 (6))/C 62 *
Dielectric Constant (25C, 100Hz)	4.5 *
Dielectric Strength	410 v/mil *
Volume Resistivity	8 x 10 ¹⁴ ohm-cm *

Engineering Excellence

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